



QUALCOMM

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9 October 2015

Mr. Xavier Piednoir
Ms. Susanna Kooistra
ETSI, MCC
650, route des Lucioles
06921 Sophia-Antipolis
France

Subject: Nomination of candidate for the 3GPP TSG CT WG6 Vice-Chairman

Dear Mr. Piednoir and Ms. Kooistra:

I am pleased to inform you that Qualcomm, through its ATIS 3GPP affiliation, is nominating Michele Berionne as a candidate for the position of 3GPP TSG CT WG6 Vice-Chairman at the upcoming election in CT6#78.

Michele will be trained to comply with all applicable antitrust/competition laws and regulations while acting in her capacity as TSG CT WG6 Vice Chairman.

In proposing Michele for the position of 3GPP TSG CT WG6 Vice-Chairman, Qualcomm will fully support Michele in the vice-chairmanship role. Qualcomm remains fully committed to the success of 3GPP and its diverse ecosystem.

A brief curriculum vitae of Michele is attached.

Best Regards,

A handwritten signature in black ink, appearing to read "Edward G. Tiedemann, Jr." with a stylized flourish at the end.

Edward G. Tiedemann, Jr.
Senior Vice-President, *Engineering*
QUALCOMM Technologies, Inc.

Michele Berionne

Michele graduated in 2002 with a Master's degree in Telecommunications Engineering from the Università di Roma "La Sapienza", Italy.

Michele has been working at QUALCOMM since 2006. He initially worked in the IMS development team. Since 2008, he has been leading a software development team for the UICC card module in the chipsets, focusing on interaction between the UICC and other parts of the system. He started attending CT WG6 in January 2011 and has been Vice-Chairman since November 2013. He also attends ETSI SCP TEC meetings.